

Final Product/Process Change Notification Document #:FPCN25678XA Issue Date:14 Mar 2025

Title of Change:	Qualification of onsemi CZ4 Roznov as an alternative wafer fab site for HDG4D and HDG4 Technology		
Proposed First Ship date:	21 Jun 2025 or earlier if approved by customer		
Contact Information:	Contact your local onse	mi Sales Office	
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.		
Additional Reliability Data:	Contact your local onsemi Sales Office or Jacob.Saliba@onsemi.com		
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com		
Marking of Parts/ Traceability of Change:	Material will be traceable with onsemi lot trace code & date code.		
Change Category:	Wafer Fab Change		
Change Sub-Category(s):	Manufacturing Site Addition		
Sites Affected:			
onsemi Sites		External Foundry/Subcon Sites	
onsemi Roznov, Czech Republic		None	

Description and Purpose:

onsemi wants to notify its customers regarding the qualification of HDG4D, HDG4 technology at onsemi CZ4 Roznov, Czech Republic wafer fab, to enable expanded capacity for this technology.

FAB Site	Before	After
Gate Driver	onsemi Bucheon, Korea	onsemi Bucheon, Korea
HDG4D/HDG4	Diodes, Maine, United States	Diodes, Maine, United States
		onsemi Roznov, Czech Republic
Back grind location	onsemi Bucheon, Korea	onsemi Bucheon, Korea
	Diodes, Maine, United States	Diodes, Maine, United States
		onsemi Roznov, Czech Republic

onsemi wishes to promptly inform our customer of our intent to expand this portion of our portfolio so that you may plan appropriately and effectively for this change.

There are no product material changes as a result of this change.

There is no product marking change as a result of this change.

onsemi

Reliability Data Summary:

QV DEVICE NAME: FAN7380MX RMS: 087670 PACKAGE: SOIC8N

Test	Specification	Condition	Interval	Results
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260°C, Pre TC, uHAST, HAST for surface mount pkgs only		0/693
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, biased	96 hours	0/231
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100% max rated Vcc	1008 hours	0/231
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hours	0/231
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cycles	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	Ta=130°C, 85% RH, 18.8psig, unbiased	96 hours	0/231

QV DEVICE NAME: FAD6263M1X RMS: 0100378 PACKAGE: SOIC16

Test	Specification	Condition	Interval	Results
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs	0/231
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs	0/231
Early Life Failure Rate	JESD22-A108	Ta=125°C, 100 % max rated Vcc	48 hrs	0/2400
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C, Pre TC, uHAST, THB for surface mount pkgs only		0/693
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/231
Temperature Humidity Bias	JESD22-A101	85°C, 85% RH, 18.8psig, bias	1008 hrs	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231

QV DEVICE NAME: FSB50550BB

RMS: U89296

PACKAGE.	351013	

Test	Specification	Condition	Interval	Results
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs	0/27
Preconditioning	J-STD-020 JESD-A113	MSL 3 @ 260 °C, Pre TC for surface mount pkgs only	-	0/27
Temperature Cycling	JESD22-A104	Ta= -40°C to +125°C	200 сус	0/27

Electrical Characteristics Summary:

Electrical characteristics are not impacted.



List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
FAN7382MX	FAN7380MX
FSB50550ASE	FSB50550BB, FAD6263M1X
FSB50550AT	FSB50550BB, FAD6263M1X
FSB50550BB	FSB50550BB, FAD6263M1X
FSB50550BS	FSB50550BB, FAD6263M1X
FNB41060	FSB50550BB, FAD6263M1X
FNB41060B2	FSB50550BB, FAD6263M1X
FNB41560	FSB50550BB, FAD6263M1X
FNB41560B2	FSB50550BB, FAD6263M1X
FSB50550AS	FSB50550BB, FAD6263M1X
FSB50450US	FSB50550BB, FAN7380MX
FSB50450S	FSB50550BB, FAN7380MX
FSB50450AS	FSB50550BB, FAD6263M1X
FSB50325AP	FSB50550BB, FAD6263M1X
FSB50250US	FSB50550BB, FAN7380MX
FSB50250AT	FSB50550BB, FAD6263M1X
FSB50250AS	FSB50550BB, FAD6263M1X
FSB50250AP	FSB50550BB, FAD6263M1X
FND43060T2	FSB50550BB, FAD6263M1X
FNC42060F7V	FSB50550BB, FAD6263M1X
FNC42060F5	FSB50550BB, FAD6263M1X
FNC42060F2	FSB50550BB, FAD6263M1X
FNC42060F	FSB50550BB, FAD6263M1X
FNB43060T2	FSB50550BB, FAD6263M1X
FNA41060B7V	FSB50550BB, FAD6263M1X
FNA41560	FSB50550BB, FAD6263M1X
FNA41560B2	FSB50550BB, FAD6263M1X
FNA41560B5	FSB50550BB, FAD6263M1X
FNA41560T2	FSB50550BB, FAD6263M1X



Final Product/Process Change Notification Document #:FPCN25678XA Issue Date:14 Mar 2025

FNB40560	FSB50550BB, FAD6263M1X
FAN73832MX	FAN7380MX
FAN7842MX	FAN7380MX
FAN7382M1X	FAN7380MX
NFA50460R4B	FSB50550BB, FAD6263M1X
NFA50460R47	FSB50550BB, FAD6263M1X
NFA42060R42	FSB50550BB, FAD6263M1X
NFA41560R42	FSB50550BB, FAD6263M1X
NBC9624	FSB50550BB, FAD6263M1X
NBC9620	FSB50550BB, FAD6263M1X
NBC9616	FSB50550BB, FAN7380MX
NBC9615	FSB50550BB, FAN7380MX
NBC9614	FSB50550BB, FAN7380MX
NBC9613	FSB50550BB, FAN7380MX
FSBB30CH60C	FSB50550BB, FAN7380MX
FSB50825US	FSB50550BB, FAN7380MX
FSB50825AS	FSB50550BB, FAD6263M1X
FSB50825AB	FSB50550BB, FAD6263M1X
FSB50550US	FSB50550BB, FAN7380MX